

ABSTRACT OF THE DISCLOSURE

A method of forming a solid inter-layer conductive rod. A printed circuit board comprising an insulating core layer, a first conductive layer and a second conductive layer is provided. The insulating core layer is sandwiched between the first conductive layer and the second conductive layer. A first opening that exposes a portion of the insulating core layer is formed in the first conductive layer. The exposed insulating core layer is removed by laser drilling to form a second opening that exposes a portion of the second conductive layer. An electroplating process is conducted using the second conductive layer as a negative electrode so that conductive material solidly fills the first opening and the second opening to form a solid conductive rod.

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